



BURN-IN SOCKETS

for QFN – TSOP – SOP – LGA – eMMC – BGA

01

Swiss Manufacturing Plant



This building served for the production of Swiss precision watches for a period of 70 years.

In 1984 the facility was purchased, completely renovated and high technology fully automated production equipment was installed for the production of precision interconnection products.

In 1992 the trademark

E-tec

was registered to cover the complete interconnect product range.

As of 1993 a world-wide sales & distribution network was established to offer fast and efficient service regardless of location.

In addition to the interconnection products E-tec also supplies high quality screw machine parts as well as customized injection moulded and machined products. Our innovative approach to new product development allows us to offer the service, quality and competitive prices our customers demand. Whatever your requirement, be it high volume commodity product or low quantity custom special, **E-tec**, the “**Swiss Connection**” will endeavour to satisfy your requirements.

For any further details please contact E-tec or your closest sales office.

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Burn-In Sockets MPS Series

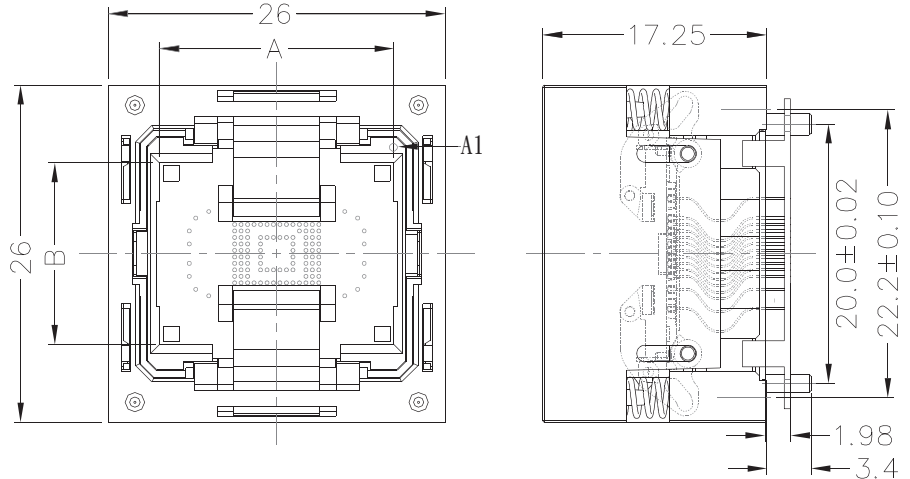
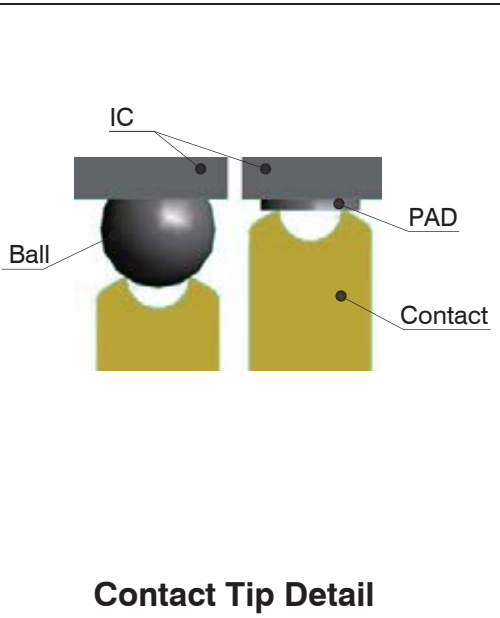
OPEN TOP eMMC SOCKET



Open Top Style. Accommodates Chip Scale Package with 0.5mm pitch.
 Compact size and low actuation force.
 4-point pinch design for enhanced electrical contact.
 Field exchangeable package location plate.
 "U" contact supports any pad or solder ball shape and composition.



Please note, we will always request the chip data to ensure we offer a compatible socket.



You may request any specific socket dimension from info@e-tec.com
 For top view socket dimension pls. ref. to separate catalog page

Applicable IC	Specifications									
<table border="1"> <tr> <td>A</td> <td>10.00/13.00/16.00/18.00</td> <td>±0.10 mm</td> </tr> <tr> <td>B</td> <td>11.50/12.00/14.00</td> <td>±0.10 mm</td> </tr> <tr> <td>C</td> <td>0.80/1.00/1.50</td> <td>±0.05 mm</td> </tr> </table>	A	10.00/13.00/16.00/18.00	±0.10 mm	B	11.50/12.00/14.00	±0.10 mm	C	0.80/1.00/1.50	±0.05 mm	<p>Mechanical data</p> <p>Contact life: 25,000 cycles Contact Normal Force: 3-5g Per Pin Operation Force: 2.0Kg max.</p> <p>Material</p> <p>Insulator (RoHS compliant): PES, PEI Contact (RoHS compliant): Beryllium Copper Alloy Contact plating: Gold cover Nickel</p> <p>Electrical data</p> <p>Contact resistance: < 30 mΩ Current rating: 1A Insulation resistance at 500V DC: 1,000 mΩ</p> <p>Operating temperature: -55°C to +175°C</p>
A	10.00/13.00/16.00/18.00	±0.10 mm								
B	11.50/12.00/14.00	±0.10 mm								
C	0.80/1.00/1.50	±0.05 mm								

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

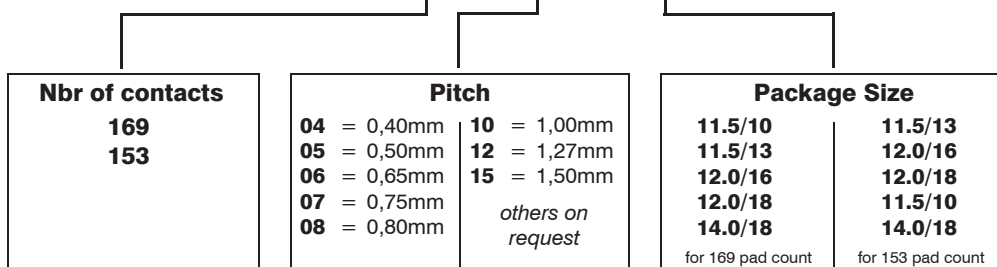
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

MPS - x x x - 05 - xx.x/xx



Burn-In Sockets MPS Series

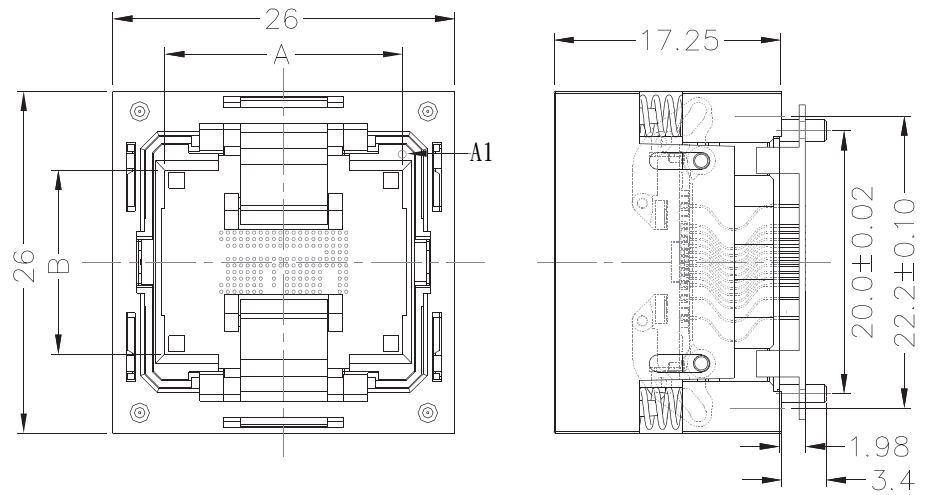
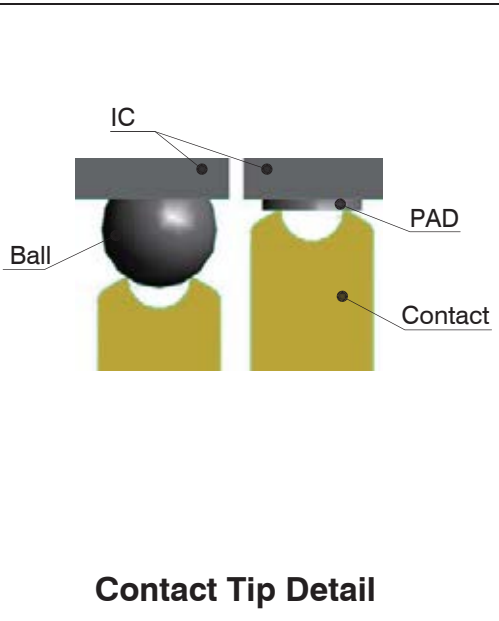
OPEN TOP eMMC SOCKET



Open Top Style. Accommodates Chip Scale Package with 0.5mm pitch.
 Compact size and low actuation force.
 4-point pinch design for enhanced electrical contact.
 Field exchangeable package location plate.
 "U" contact supports any pad or solder ball shape and composition.



Please note, we will always request the chip data to ensure we offer a compatible socket.

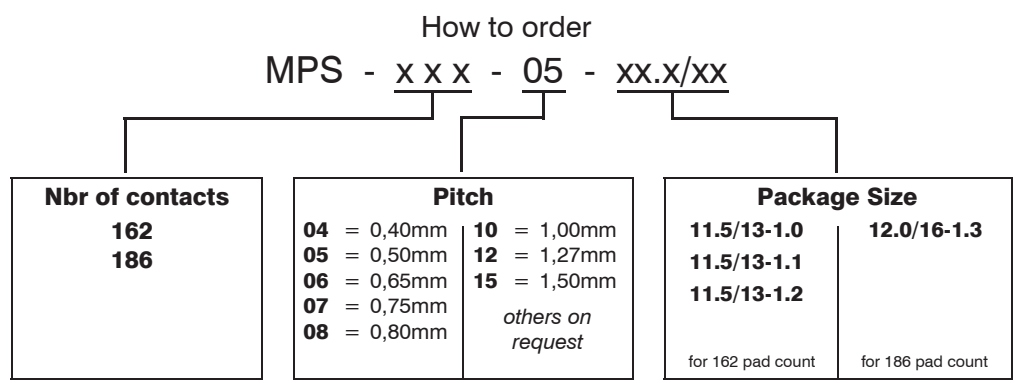


You may request any specific socket dimension from info@e-tec.com
 For top view socket dimension pls. ref. to separate catalog page

Applicable IC	Specifications									
<table border="1" style="margin-top: 10px;"> <tr> <td>A</td> <td>13.00/16.00</td> <td>±0.10 mm</td> </tr> <tr> <td>B</td> <td>11.50/12.00</td> <td>±0.10 mm</td> </tr> <tr> <td>C</td> <td>1.00/1.10/1.20/1.30</td> <td>±0.10 mm</td> </tr> </table>	A	13.00/16.00	±0.10 mm	B	11.50/12.00	±0.10 mm	C	1.00/1.10/1.20/1.30	±0.10 mm	<p>Mechanical data</p> <p>Contact life 25,000 cycles Contact Normal Force 3-5g Per Pin Operation Force 2.0Kg max.</p> <p>Material</p> <p>Insulator (RoHS compliant) PES , PEI Contact (RoHS compliant) Beryllium Copper Alloy Contact plating Gold cover Nickel</p> <p>Electrical data</p> <p>Contact resistance < 30 mΩ Current rating 1A Insulation resistance at 500V DC 1,000 mΩ</p> <p>Operating temperature -55°C to +175°C</p>
A	13.00/16.00	±0.10 mm								
B	11.50/12.00	±0.10 mm								
C	1.00/1.10/1.20/1.30	±0.10 mm								

Recommendations:

Solder paste – Please use a solder paste w/o any silver!
 E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!
 For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)
 For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

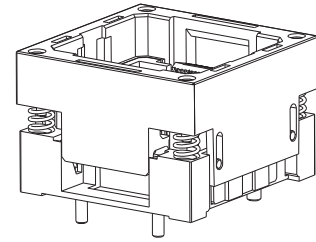


Burn-In Sockets MPS Series

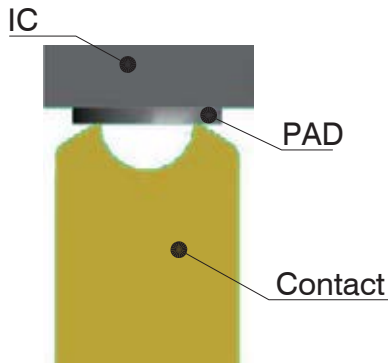
OPEN TOP LGA SOCKET



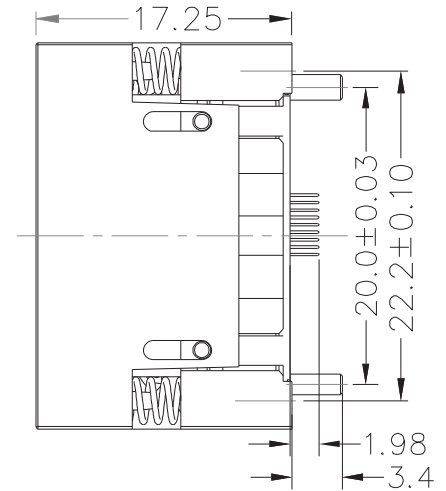
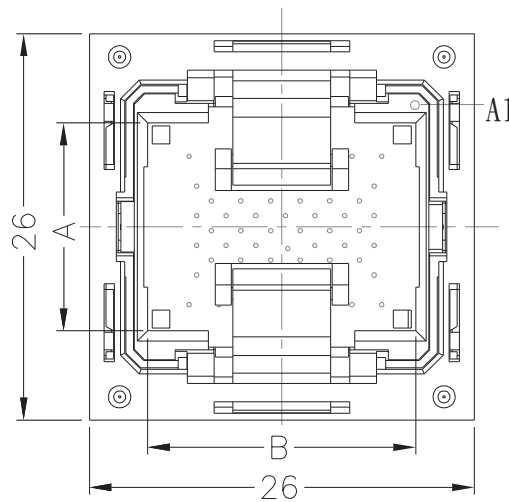
Open Top Style. Accommodates LGA package with 1.0mm pitch.
 Compact size and low actuation force.
 4-Point pinch design for enhanced electrical contact.
 Field exchangeable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.



Contact Tip Detail



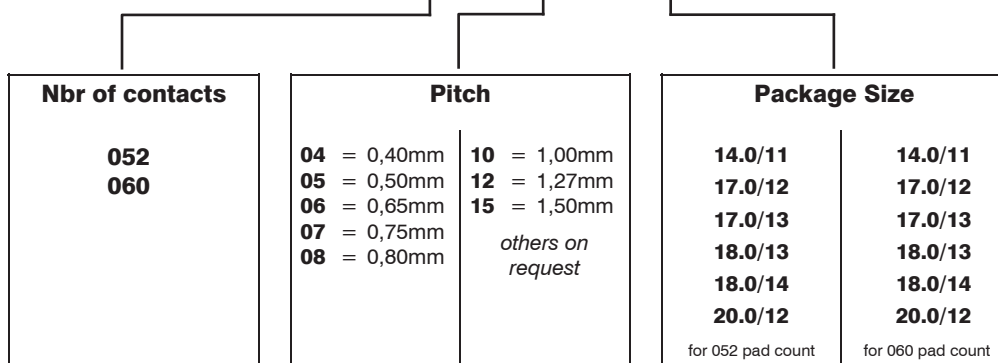
You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Applicable IC		Specifications	
		Mechanical data	
		Contact life	25,000 cycles
		Contact Normal Force	3-5g Per Pin
		Operation Force	2.0Kg max.
		Material	
		Insulator (RoHS compliant)	PES, PEI
		Contact (RoHS compliant)	Beryllium Copper Alloy
		Contact plating	Gold cover Nickel
		Electrical data	
		Contact resistance	< 30 mΩ
		Current rating	1A
		Insulation resistance at 500V DC	1,000 mΩ
		Operating temperature	-55°C to +175°C
Recommendations:			
Solder paste – Please use a solder paste w/o any silver!		Solder profile – Please refer to our website www.e-tec.com	
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!			
For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)			
For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.			

How to order

MPS - xxx - 10 - xx.x/xx

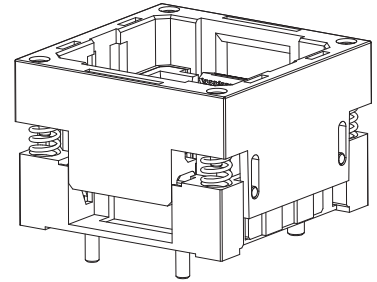


Burn-In Sockets MPS Series

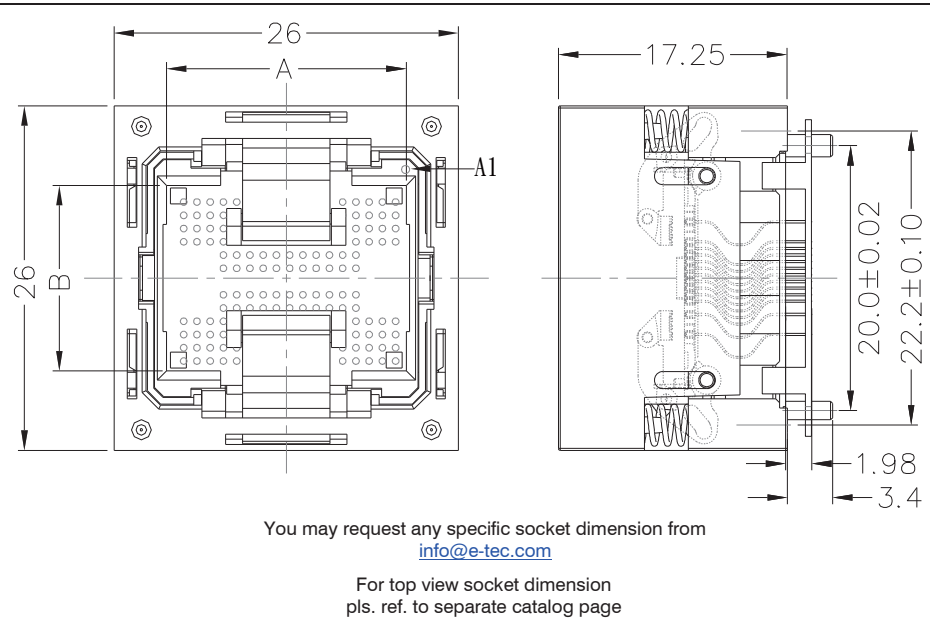
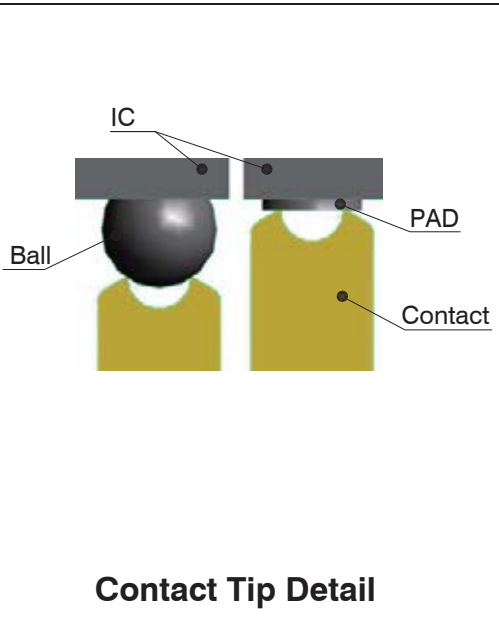
OPEN TOP BGA SOCKET



Open Top Style. Accommodates Chip Scale package with 1.0mm pitch.
 Compact size and low Actuation Force.
 4-Point pinch design for enhanced electrical contact.
 Field exchangeable package location plate.
 "U" contact supports any type of solder ball shape and composition.



Please note, we will always request the chip data to ensure we offer a compatible socket.



Applicable IC	Specifications									
<table border="1"> <tr> <td>A</td> <td>12.00/14.00</td> <td>±0.10 mm</td> </tr> <tr> <td>B</td> <td>16.00/16.50/18.00</td> <td>±0.10 mm</td> </tr> <tr> <td>C</td> <td>0.78/0.98/1.00/1.50</td> <td>±0.05 mm</td> </tr> </table>	A	12.00/14.00	±0.10 mm	B	16.00/16.50/18.00	±0.10 mm	C	0.78/0.98/1.00/1.50	±0.05 mm	<p>Mechanical data</p> <p>Contact life: 25,000 cycles Contact Normal Force: 3-5g Per Pin Operation Force: 2.0Kg max.</p> <p>Material</p> <p>Insulator (RoHS compliant): PES, PEI Contact (RoHS compliant): Beryllium Copper Alloy Contact plating: Gold cover Nickel</p> <p>Electrical data</p> <p>Contact resistance: < 30 mΩ Current rating: 1A Insulation resistance at 500V DC: 1,000 mΩ</p> <p>Operating temperature: -55°C to +175°C</p>
A	12.00/14.00	±0.10 mm								
B	16.00/16.50/18.00	±0.10 mm								
C	0.78/0.98/1.00/1.50	±0.05 mm								

Recommendations:

Solder paste – Please use a solder paste w/o any silver!
 E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!
 For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)
 For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

MPS - x x x - 10 - xx.x/xx

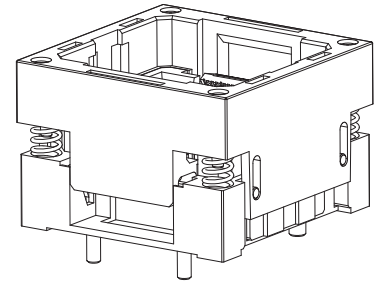
Nbr of contacts	Pitch	Package Size
088	04 = 0,40mm	12.0/16-0.98 for 088 pad count
132	05 = 0,50mm	14.0/16.5-0.78
136	06 = 0,65mm	14.0/16.5-0.98
152	07 = 0,75mm	12.0/18-0.78
	08 = 0,80mm	12.0/18-0.98
	10 = 1,00mm	12.0/18-1.5
	12 = 1,27mm	for 152 pad count
	15 = 1,50mm	for 136 pad count
	others on request	for 132 pad count

Burn-In Sockets MPS Series

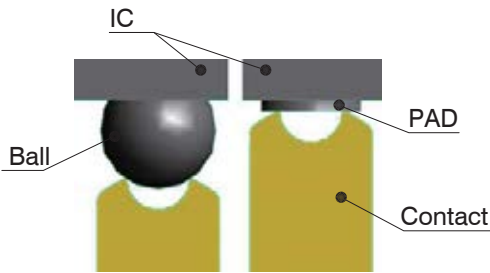
OPEN TOP BGA SOCKET



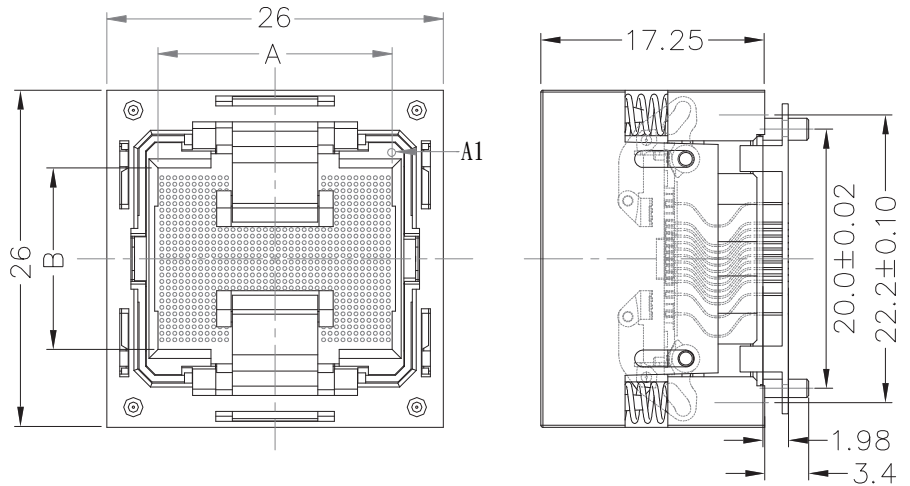
Open Top Style. Compact size and low Actuation Force.
 Accommodates BGA chip package with 0.50/0.65/0.80/1.00mm pitch.
 4-Point pinch design for enhanced electrical contact.
 Unique mechanism to eliminate solder ball sticking.
 Field replaceable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.



Contact Tip Detail



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life: 25,000 cycles
 Contact Normal Force: 3-5g Per Pin
 Operation Force: 2.0kg min.

Material

Insulator (RoHS compliant): PES, PEI
 Contact (RoHS compliant): Beryllium Copper Alloy
 Contact plating: Gold cover Nickel

Electrical data

Contact resistance: < 30 mΩ
 Current rating: 1A
 Insulation resistance at 500V DC: 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

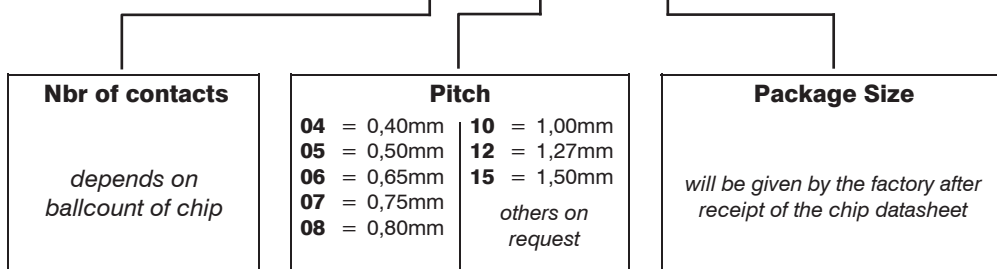
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

MPS - xxx - xx - xx.x/xx

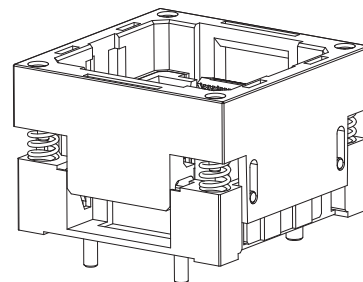


Burn-In Sockets MPS Series

OPEN TOP BGA SOCKET



Open Top Style. Compact size and low Actuation Force.
 Accommodates BGA chip package with 0.50/0.65/0.80/1.00mm pitch.
 4-Point pinch design for enhanced electrical contact.
 Unique mechanism to eliminate solder ball sticking.
 Field replaceable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.

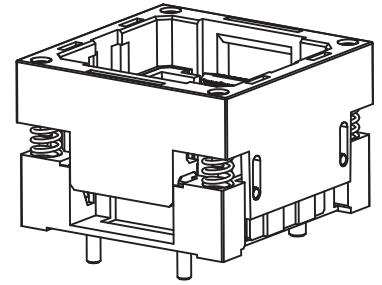
Pitch	No. of Contacts	Package Size(mm)	Part Number
0.5	40	8x9.2	MPS-040-05-8.0/9.2
	48	6x4	MPS-048-05-6.0/4
	56	6x6	MPS-056-05-6.0/6
	64	5x5	MPS-064-05-5.0/5
	84	6x6	MPS-084-05-6.0/6
	88	7x7	MPS-088-05-8.0/8
	105	6x6	MPS-105-05-6.0/6
0.8	141	11.5x13	MPS-141-05-11.5/13
	25	5x5	MPS-025-08-5.0/5
	30	5x5	MPS-030-08-5.0/5
	48	6x10	MPS-048-08-6.0/10
	48	6x11	MPS-048-08-6.0/11
	48	6x8	MPS-048-08-6.0/8
	48	6x9	MPS-048-08-6.0/9
	48	6.15x8.15	MPS-048-08-6.15/8.15
	48	8x10	MPS-048-08-8.0/10
	48	9x11	MPS-048-08-9.0/11
	48	9.5x12	MPS-048-08-9.5/12
	48	10.95x11.95	MPS-048-08-10.95/11.95
	48	11x12	MPS-048-08-11/12
	54	8x8	MPS-054-08-8.0/8
	56	7x9	MPS-056-08-7.0/9
	56	8x10	MPS-056-08-8.0/10
	56	8x11.6	MPS-056-08-8.0/11.6
	56	8x11.6	MPS-056-08-8/11.6
	56	8x13	MPS-056-08-8.0/13
	59	8x11.6	MPS-056-08-8.0/11.6
	60	8x10	MPS-060-08-8.0/10
	60	8x11.6	MPS-060-08-8.0/11.6
	60	11x13	MPS-060-08-11.0/13
	63	7x11	MPS-063-08-7.0/11
	64	7x7	MPS-064-08-7.0/7
64	8x11	MPS-064-08-8.0/11	
64	8.1x11.1	MPS-064-08-8.1/11.1	

Burn-In Sockets MPS Series

OPEN TOP BGA SOCKET



Open Top Style. Compact size and low Actuation Force.
 Accommodates BGA chip package with 0.50/0.65/0.80/1.00mm pitch.
 4-Point pinch design for enhanced electrical contact.
 Unique mechanism to eliminate solder ball sticking.
 Field replaceable package location plate.



Please note, we will always request the chip data to ensure we offer a compatible socket.

Pitch	No. of Contacts	Package Size(mm)	Part Number
1.0	64	7.95x8.95	MPS-064-10-7.95/8.95
	64	9x9	MPS-064-10-9.0/9
	64	9x11.5	MPS-064-10-9.0/11.5
	64	10.95x11.95	MPS-064-10-10.95/11.95
	66	7.47x11.02	MPS-066-10-7.47/11.02
	72	10x10	MPS-072-10-10.0/10
	80	7x9	MPS-080-10-7.0/09
	80	8x8	MPS-080-10-8.0/08
	80	8x10	MPS-080-10-8.0/10
	80	8x11	MPS-080-10-8.0/11
	80	9x11.5	MPS-080-10-9.0/11.5
	81	8x8	MPS-081-10-8.0/08
	81	14x18	MPS-081-10-14.0/18

Burn-In Sockets OTZ Series

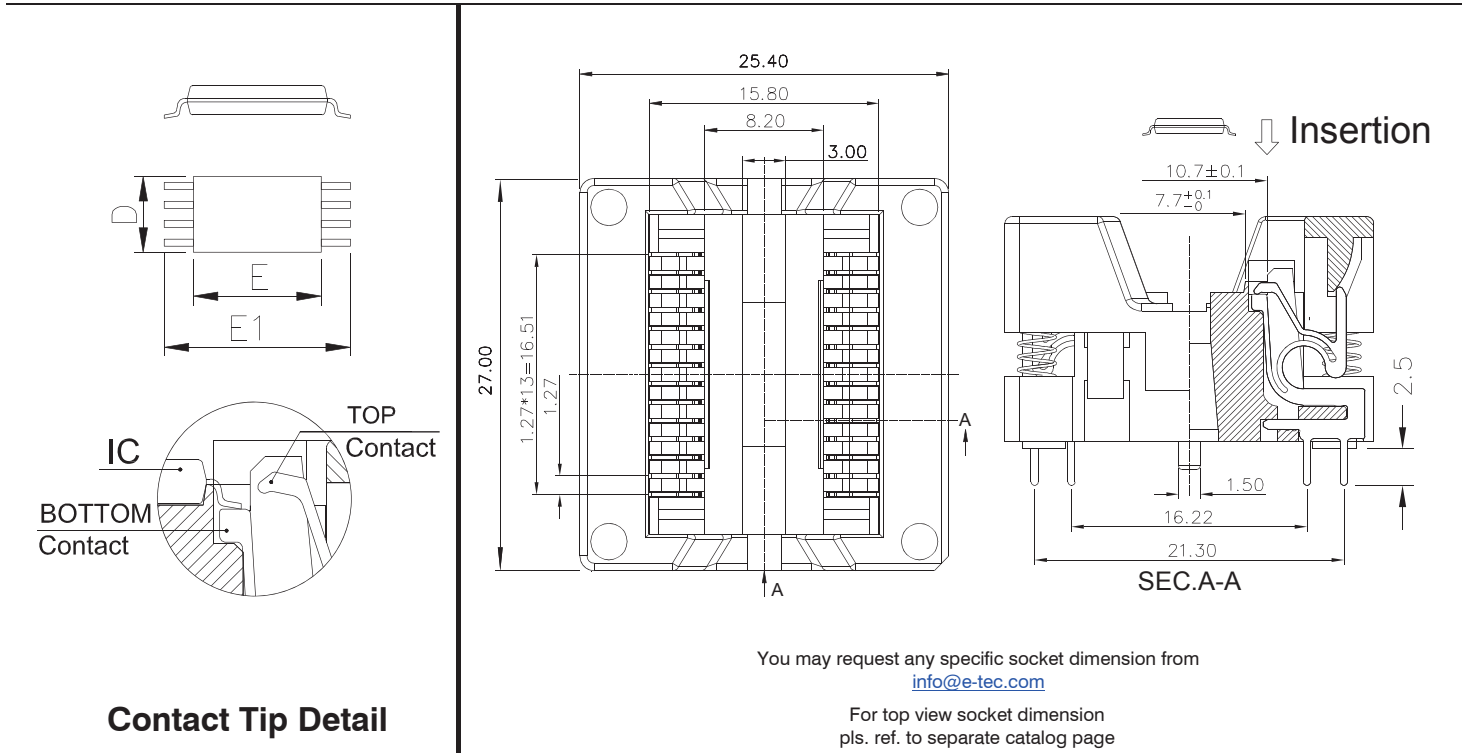
SOP SOCKET



Open top thru-hole style for Small Outline chip Packages.
 Zero Insertion Force designed for automatic loading.
 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



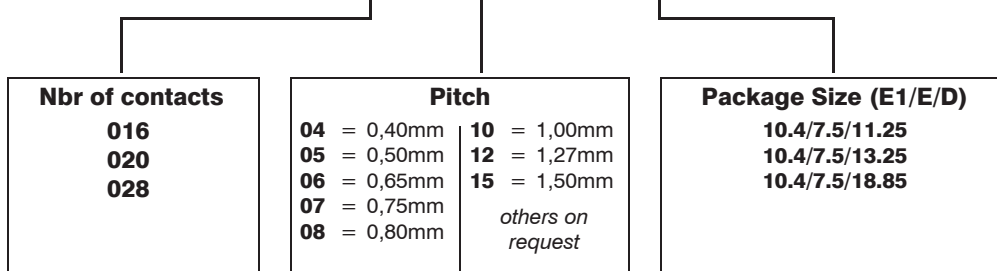
Please note, we will always request the chip data to ensure we offer a compatible socket.



Specifications			
Mechanical data		Electrical data	
Contact life	15,000 cycles	Contact resistance	< 30 mΩ
Contact Normal Force	18g Per Pin	Current rating	10mA
Operation Force	1.0Kg max.	Insulation resistance at 500V DC	1,000 mΩ
Material		Operating temperature	
Insulator (RoHS compliant)	PES , PEI	-55°C to +175°C	
Contact (RoHS compliant)	Beryllium Copper Alloy		
Contact plating	Gold cover Nickel		
Recommendations:			
Solder paste – Please use a solder paste w/o any silver!		Solder profile – Please refer to our website www.e-tec.com	
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!			
For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)			
For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.			

How to order

OTZ - x x x - 12 - xx.x/xx.x/xx.x



Burn-In Sockets OTZ Series

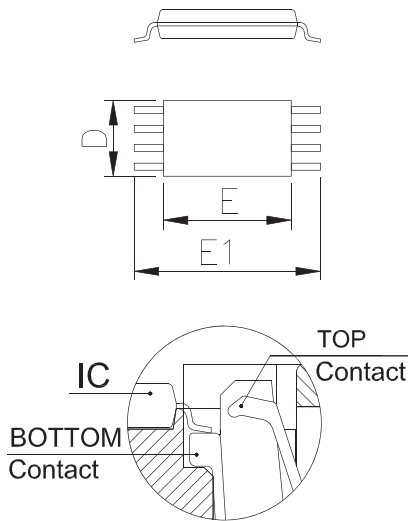
SOP SOCKET



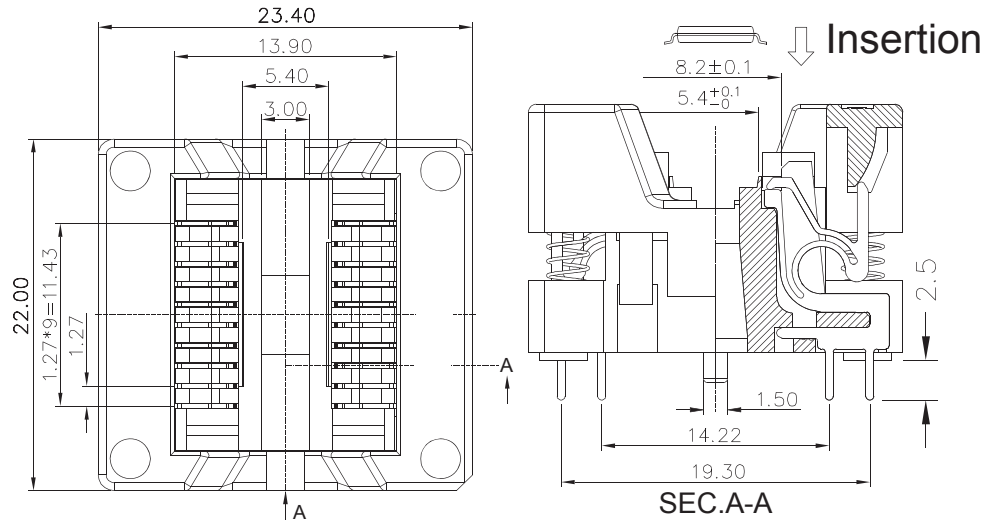
Open top thru-hole style for Small Outline chip Packages.
 Zero Insertion Force designed for automatic loading.
 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



Please note, we will always request the chip data to ensure we offer a compatible socket.



Contact Tip Detail



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For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 18g Per Pin
 Operation Force 1.0Kg max.

Material

Insulator (RoHS compliant) PES, PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 10mA
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

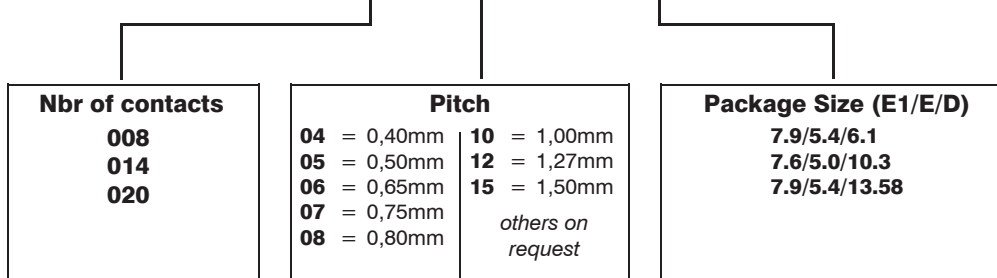
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How to order

OTZ - x x x - 12 - xx.x/xx.x/xx.x



Burn-In Sockets OTZ Series

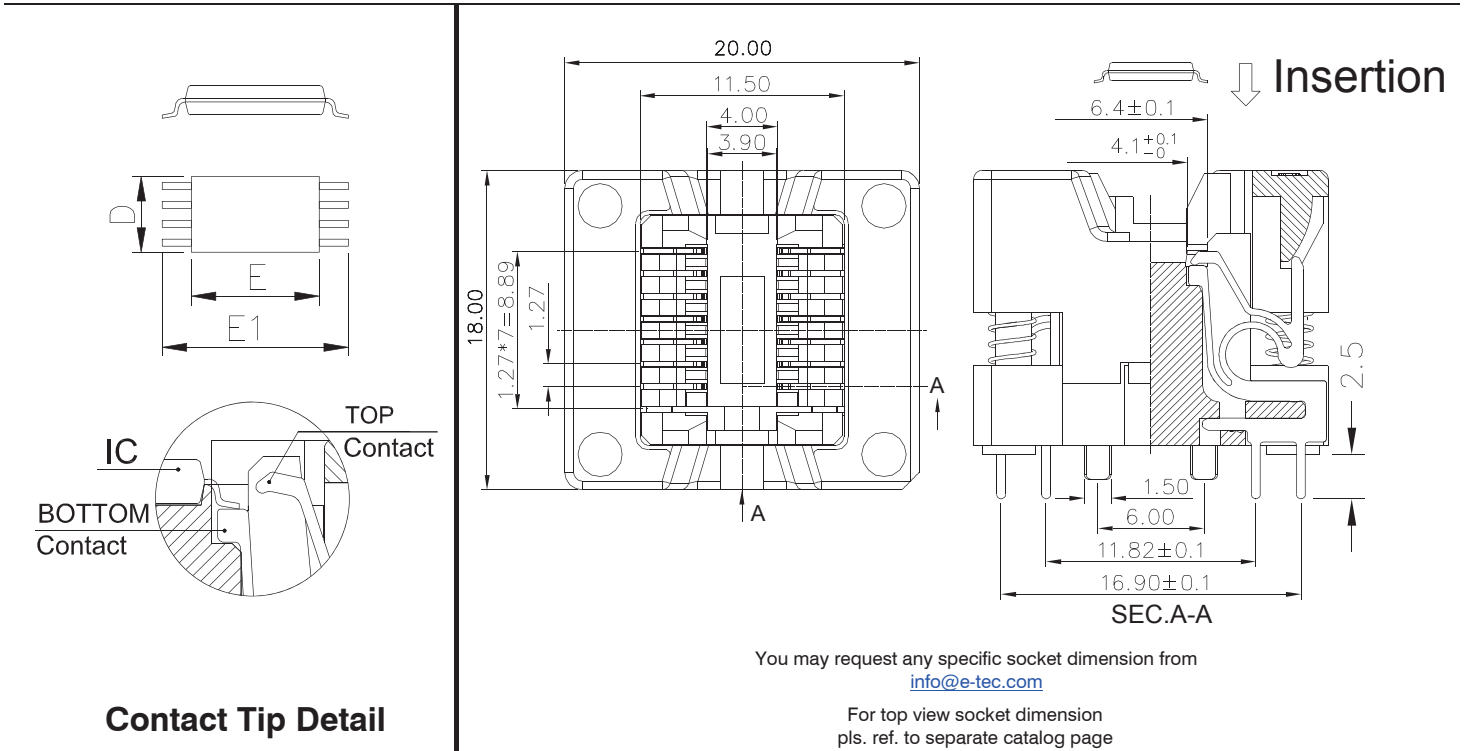
SOP SOCKET



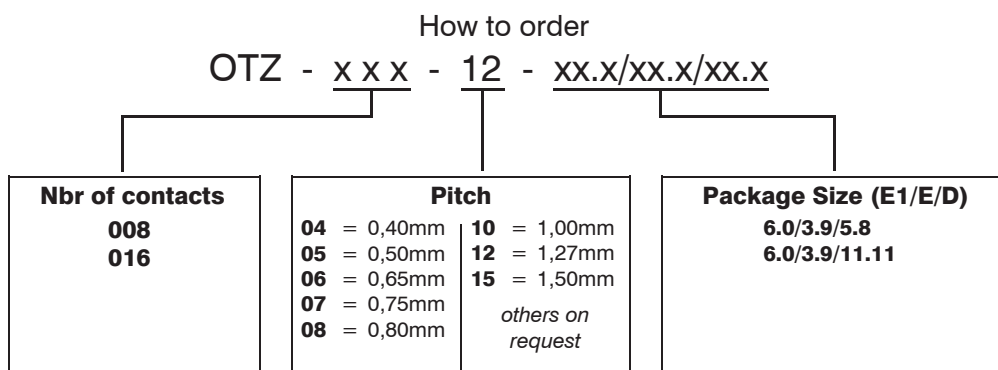
Open top thru-hole style for Small Outline chip Packages.
 Zero Insertion Force designed for automatic loading.
 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



Please note, we will always request the chip data to ensure we offer a compatible socket.



Specifications			
Mechanical data		Electrical data	
Contact life	15,000 cycles	Contact resistance	< 30 mΩ
Contact Normal Force	18g Per Pin	Current rating	10mA
Operation Force	1.0Kg max.	Insulation resistance at 500V DC	1,000 mΩ
Material		Operating temperature	
Insulator (RoHS compliant)	PES , PEI	-55°C to +175°C	
Contact (RoHS compliant)	Beryllium Copper Alloy		
Contact plating	Gold cover Nickel		
Recommendations:			
Solder paste – Please use a solder paste w/o any silver!		Solder profile – Please refer to our website www.e-tec.com	
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!			
For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)			
For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.			



Burn-In Sockets OTZ Series

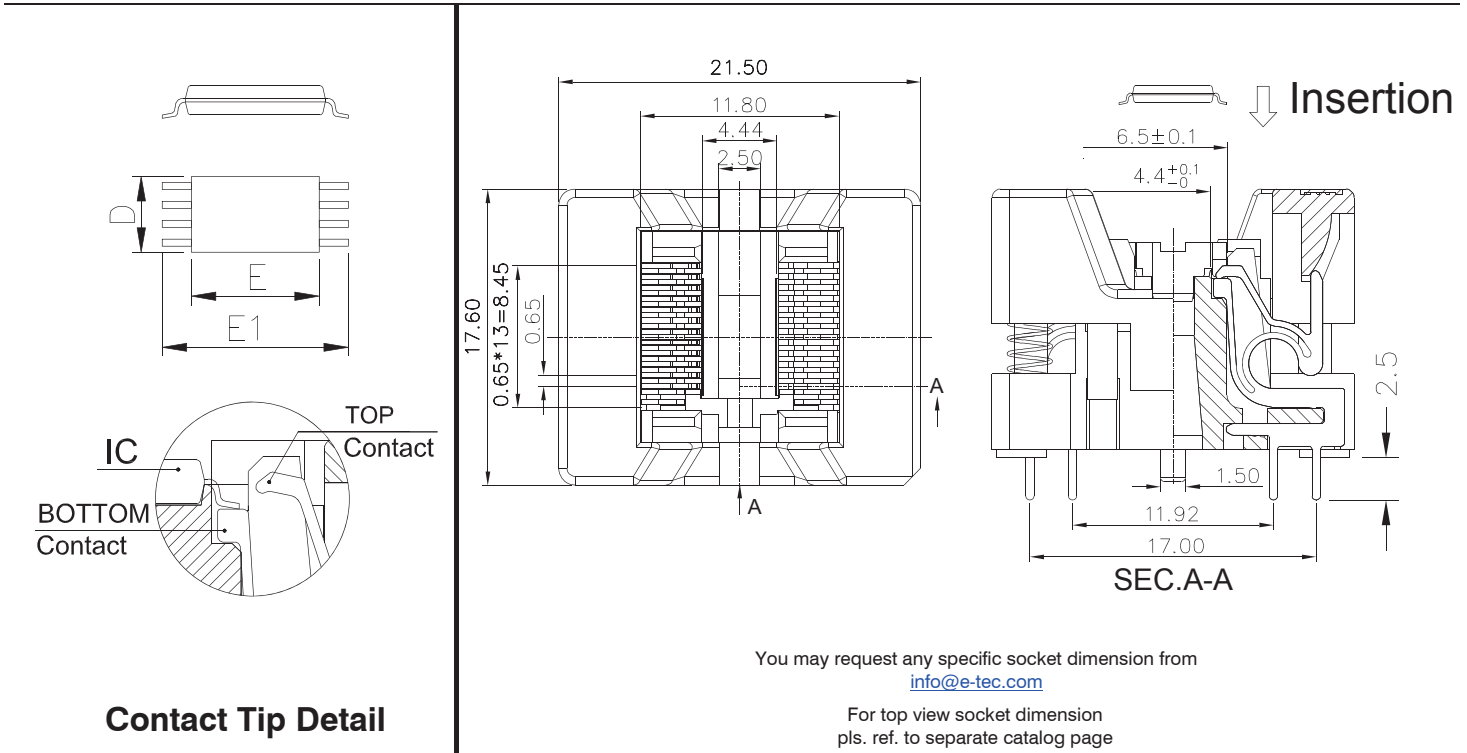
SOP SOCKET



Open top thru-hole style for Small Outline chip Packages.
 Zero Insertion Force designed for automatic loading.
 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



Please note, we will always request the chip data to ensure we offer a compatible socket.



Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 18g Per Pin
 Operation Force 1.0Kg max.

Material

Insulator (RoHS compliant) PES , PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 10mA
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

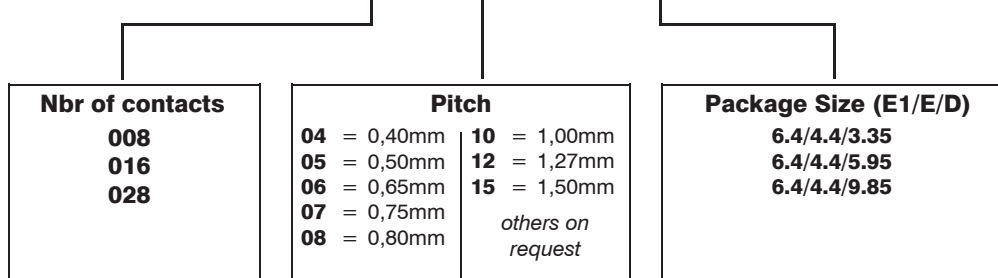
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For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

OTZ - x x x - 06 - xx.x/xx.x/xx.x



Burn-In Sockets OTZ Series

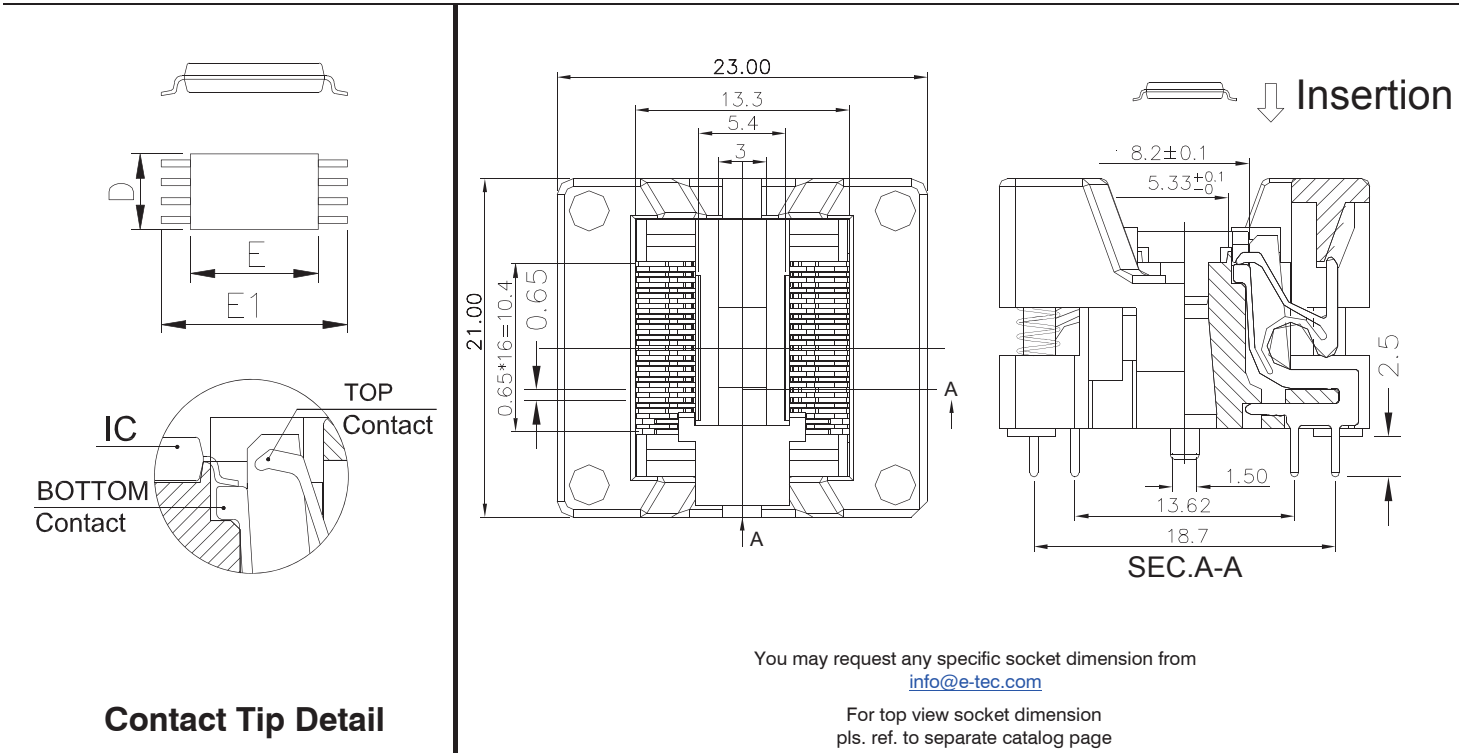
SOP SOCKET



Open top thru-hole style for Small Outline chip Packages.
 Zero Insertion Force designed for automatic loading.
 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



Please note, we will always request the chip data to ensure we offer a compatible socket.



Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 18g Per Pin
 Operation Force 1.0Kg max.

Material

Insulator (RoHS compliant) PES , PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 10mA
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

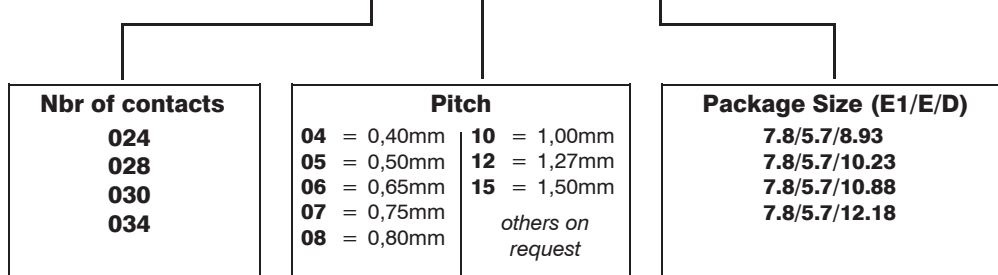
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For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

OTZ - x x x - 06 - xx.x/xx.x/xx.x



Burn-In Sockets OTZ Series

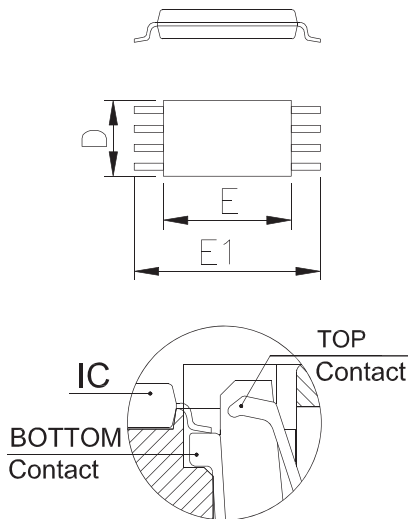
SOP SOCKET



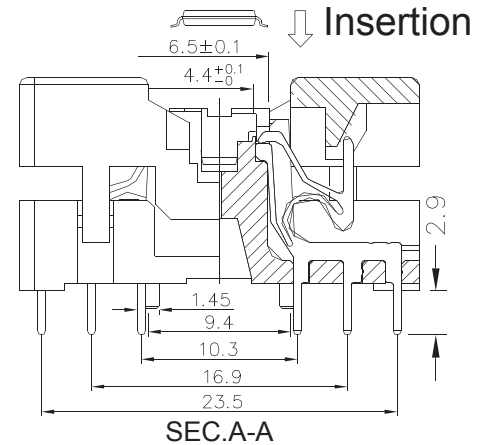
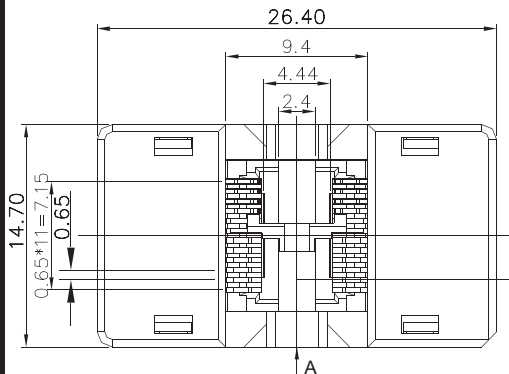
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 Highly reliable, dual pinch, pre-loaded contacts.
 Live bug insertion for 0.65/1.27mm pitch packages.
 High force contact version available for Pb-free devices (single beam type).



Please note, we will always request the chip data to ensure we offer a compatible socket.



Contact Tip Detail



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 18g Per Pin
 Operation Force 1.0Kg max.

Material

Insulator (RoHS compliant) PES, PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 10mA
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

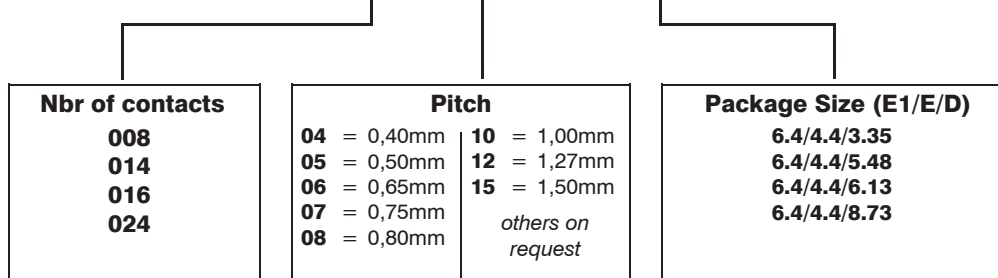
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

OTZ - x x x - 06 - xx.x/xx.x/xx.x

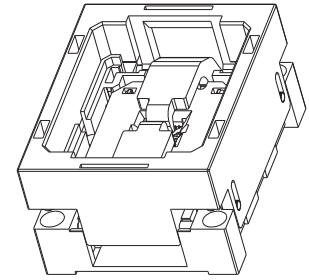


Burn-In Sockets QOT Series

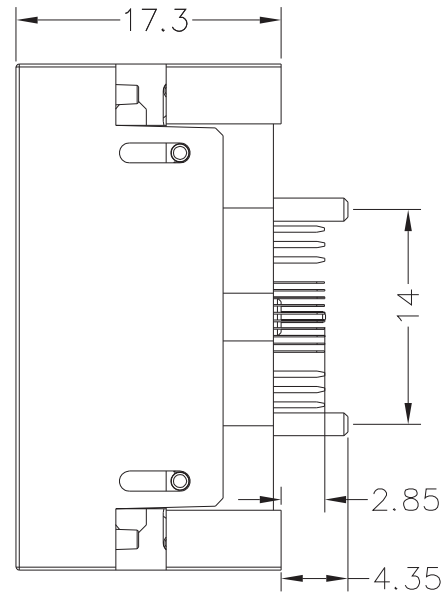
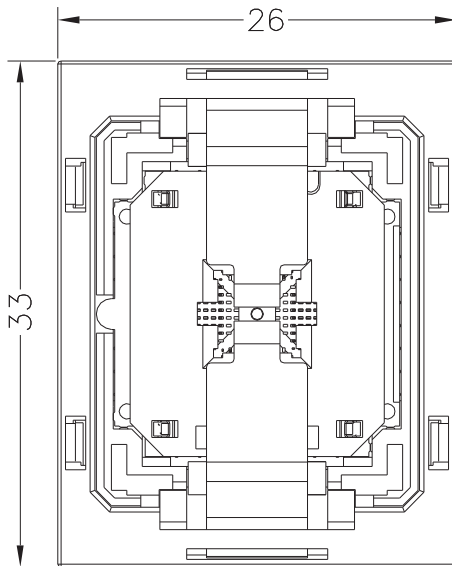
OPEN TOP QFN SOCKET



Universal Open Top Style for Thru-Hole mount
 Individual spring loaded pressure pad per device type
 Inexpensive GP insert accommodates many package sizes
 X-shape stand-off prevents package from sticking
 Accommodate 0.5~1.2mm thick packages
 (See pages 16/17 for ClamShell style)



Please note, we will always request the chip data to ensure we offer a compatible socket.



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 5-8g Per Pin
 Operation Force 2.0Kg max

Material

Insulator (RoHS compliant) PES , PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 1A
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

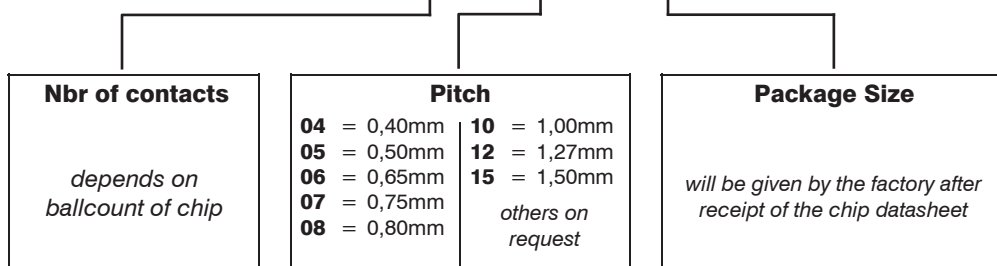
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

QOT - XXX - XX - XX.X/XX

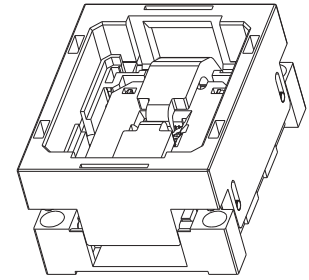


Burn-In Sockets QOT Series

OPEN TOP QFN SOCKET



Universal Open Top Style for Thru-Hole mount
 Individual spring loaded pressure pad per device type
 Inexpensive GP insert accommodates many package sizes
 X-shape stand-off prevents package from sticking
 Accommodate 0.5~1.2mm thick packages
 (See pages 16/17 for ClamShell style)



Please note, we will always request the chip data to ensure we offer a compatible socket.

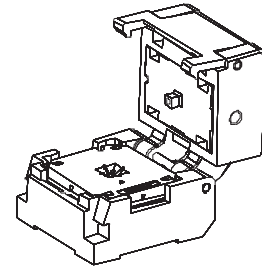
Pitch	No. of Contacts	Pad Matrix	Package Size(mm)	Part Number
0.4	12	odd	2x2	QOT-012-04-2.0/2
	16	even	3x3	QOT-016-04-3.0/3
	20	odd	3x3	QOT-020-04-3.0/3
	24	even	4x4	QOT-024-04-4.0/4
	28	odd	4x4	QOT-028-04-4.0/4
	32	even	5x5	QOT-032-04-5.0/5
	36	odd	5x5	QOT-036-04-5.0/5
	40	even	5x5	QOT-040-04-5.0/5
	44	odd	6x6	QOT-044-04-6.0/6
	48	even	6x6	QOT-048-04-6.0/6
	52	odd	7x7	QOT-052-04-7.0/7
	56	even	7x7	QOT-056-04-7.0/7
	60	odd	8x8	QOT-060-04-8.0/8
	64	even	8x8	QOT-064-04-8.0/8
	76	odd	9x9	QOT-076-04-9.0/9
	80	even	9x9	QOT-080-04-9.0/9
	84	odd	10x10	QOT-084-04-10.0/10
	88	even	10x10	QOT-088-04-10.0/10
104	even	12x12	QOT-104-04-12.0/12	
108	odd	12x12	QOT-108-04-12.0/12	
0.5	12	odd	2x2	QOT-012-05-2.0/2
	16	even	3x3	QOT-016-05-3.0/3
	12	odd	3x3	QOT-012-05-3.0/3
	20	odd	3x3	QOT-020-05-3.0/3
	24	even	4x4	QOT-024-05-4.0/4
	20	odd	4x4	QOT-020-05-4.0/4
	32	even	5x5	QOT-032-05-5.0/5
	28	odd	5x5	QOT-028-05-5.0/5
	40	even	6x6	QOT-040-05-6.0/6
	36	odd	6x6	QOT-036-05-6.0/6
	48	even	7x7	QOT-048-05-7.0/7
	44	odd	7x7	QOT-044-05-7.0/7
	56	even	8x8	QOT-056-05-8.0/8
	52	odd	8x8	QOT-052-05-8.0/8
	64	even	9x9	QOT-064-05-9.0/9
	60	odd	9x9	QOT-060-05-9.0/9
	72	even	10x10	QOT-072-05-10.0/10
	68	odd	10x10	QOT-068-05-10.0/10
88	even	12x12	QOT-088-05-12.0/12	
84	odd	12x12	QOT-084-05-12.0/12	

Burn-In Sockets QMC Series

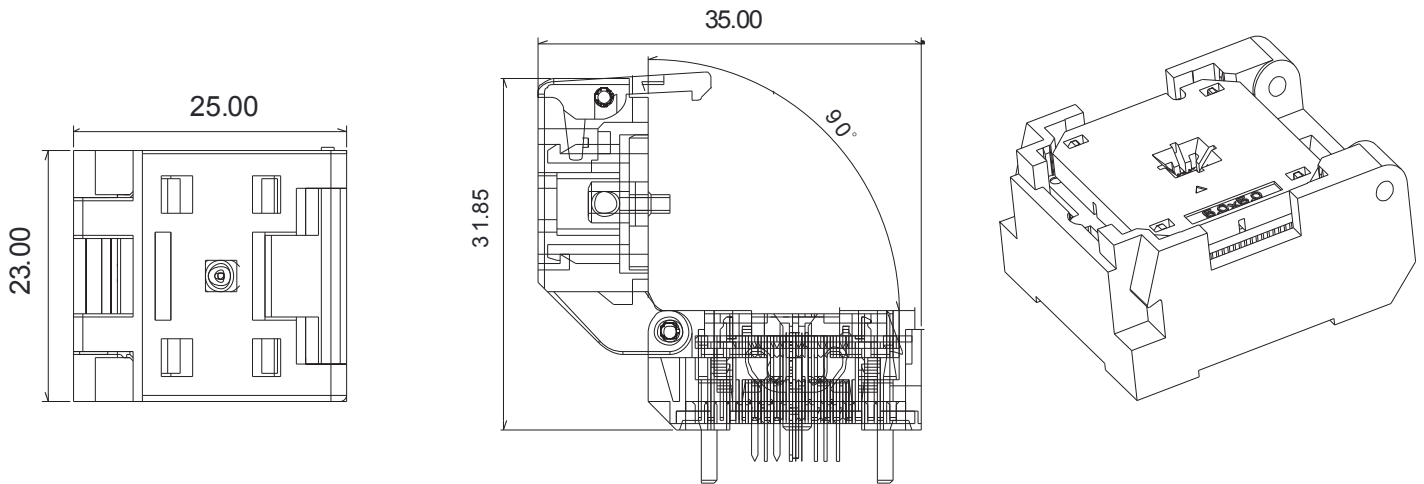
CLAMSHELL QFN SOCKET



Universal ClamShell Style for Thru-Hole mount
 Individual spring loaded pressure pad per device type
 Inexpensive GP insert accommodates many package sizes
 Opening provided on top for sensor placement
 X-shape stand-off prevents package from sticking
 Accommodate 0.5~1.2mm thick packages
 (See pages 14/15 for Open Top style)



Please note, we will always request the chip data to ensure we offer a compatible socket.



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life 15,000 cycles
 Contact Normal Force 5-8g Per Pin
 Operation Force 2.0Kg max

Material

Insulator (RoHS compliant) PES , PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 1A
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-55°C to +175°C

Recommendations:

Solder paste – Please use a solder paste w/o any silver!

Solder profile – Please refer to our website www.e-tec.com

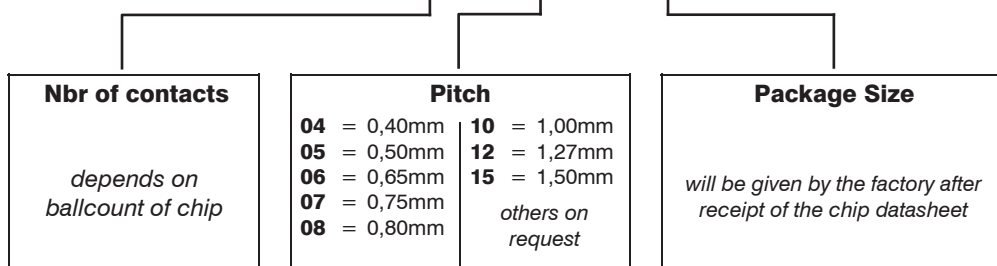
E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.

How to order

QMC - xxx - xx - xx.x/xx

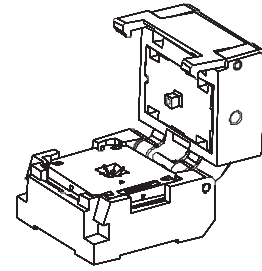


Burn-In Sockets QMC Series

CLAMSHELL QFN SOCKET



Universal ClamShell Style for Thru-Hole mount
 Individual spring loaded pressure pad per device type
 Inexpensive GP insert accommodates many package sizes
 Opening provided on top for sensor placement
 X-shape stand-off prevents package from sticking
 Accommodate 0.5~1.2mm thick packages
 (See pages 14/15 for Open Top style)



Please note, we will always request the chip data to ensure we offer a compatible socket.

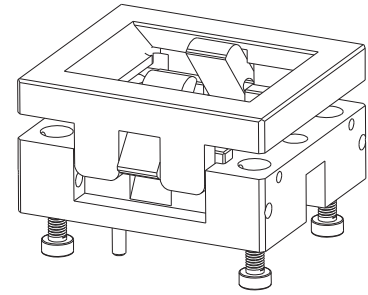
Pitch	No. of Contacts	Pad Matrix	Package Size(mm)	Part Number
0.4	12	odd	2x2	QMC-012-04-2.0/2
	16	even	3x3	QMC-016-04-3.0/3
	20	odd	3x3	QMC-020-04-3.0/3
	24	even	4x4	QMC-024-04-4.0/4
	28	odd	4x4	QMC-028-04-4.0/4
	32	even	5x5	QMC-032-04-5.0/5
	36	odd	5x5	QMC-036-04-5.0/5
	40	even	5x5	QMC-040-04-5.0/5
	44	odd	6x6	QMC-044-04-6.0/6
	48	even	6x6	QMC-048-04-6.0/6
	52	odd	7x7	QMC-052-04-7.0/7
	56	even	7x7	QMC-056-04-7.0/7
	60	odd	8x8	QMC-060-04-8.0/8
	64	even	8x8	QMC-064-04-8.0/8
	76	odd	9x9	QMC-076-04-9.0/9
	80	even	9x9	QMC-080-04-9.0/9
	84	odd	10x10	QMC-084-04-10.0/10
	88	even	10x10	QMC-088-04-10.0/10
104	even	12x12	QMC-104-04-12.0/12	
108	odd	12x12	QMC-108-04-12.0/12	
0.5	12	odd	2x2	QMC-012-05-2.0/2
	16	even	3x3	QMC-016-05-3.0/3
	12	odd	3x3	QMC-012-05-3.0/3
	20	odd	3x3	QMC-020-05-3.0/3
	24	even	4x4	QMC-024-05-4.0/4
	20	odd	4x4	QMC-020-05-4.0/4
	32	even	5x5	QMC-032-05-5.0/5
	28	odd	5x5	QMC-028-05-5.0/5
	40	even	6x6	QMC-040-05-6.0/6
	36	odd	6x6	QMC-036-05-6.0/6
	48	even	7x7	QMC-048-05-7.0/7
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	56	even	8x8	QMC-056-05-8.0/8
	52	odd	8x8	QMC-052-05-8.0/8
	64	even	9x9	QMC-064-05-9.0/9
	60	odd	9x9	QMC-060-05-9.0/9
	72	even	10x10	QMC-072-05-10.0/10
	68	odd	10x10	QMC-068-05-10.0/10
88	even	12x12	QMC-088-05-12.0/12	
84	odd	12x12	QMC-084-05-12.0/12	

Burn-In Sockets BPT Series

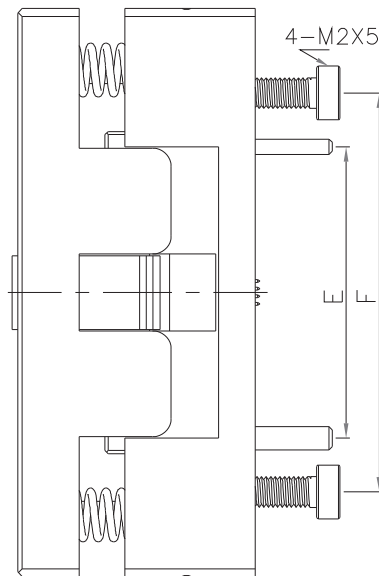
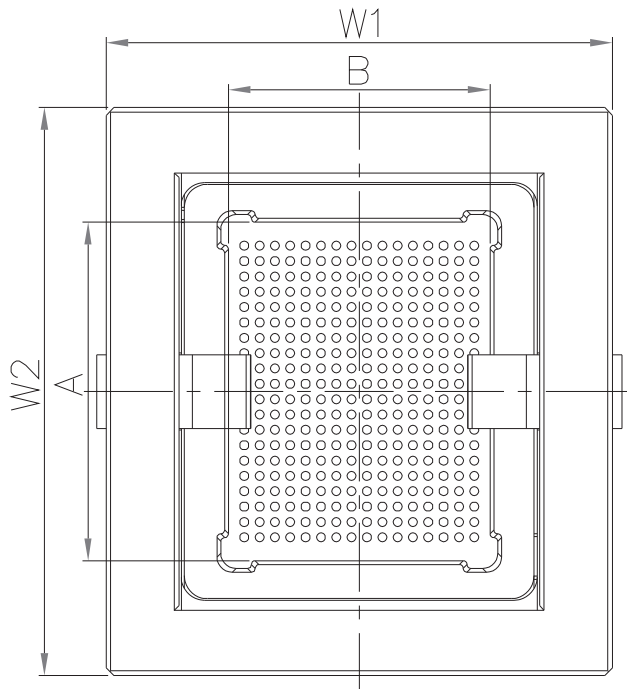
BGA PROBE PIN OPEN TOP SOCKET



Open Top Style for Solderless Compression mount
 Accommodates pitch sizes of 0.4/0.5/0.65/0.8/1.0/1.27mm
 Compact size and low Actuation Force
 4-Point pinch design for enhanced electrical contact
 Unique mechanism to eliminate solder ball sticking
 Field replaceable package location plate



Please note, we will always request the chip data to ensure we offer a compatible socket.



You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Specifications

Mechanical data

Contact life 50,000 / 8,000 cycles
 (0.5 / 0.8 pitch)
 Contact Normal Force 25 / 28g Per Pin
 Operation Force 2.0Kg max

Material

Insulator (RoHS compliant) PES , PEI
 Contact (RoHS compliant) Beryllium Copper Alloy
 Contact plating Gold cover Nickel

Electrical data

Contact resistance < 30 mΩ
 Current rating 1A / 2A (0.5 / 0.8 pitch)
 Insulation resistance at 500V DC 1,000 mΩ

Operating temperature

-40°C to +155°C

How to order

BPT - xxx - xx - xx.x/xx

Nbr of contacts

*depends on
ballcount of chip*

Pitch

04 = 0,40mm **10** = 1,00mm
05 = 0,50mm **12** = 1,27mm
06 = 0,65mm **15** = 1,50mm
07 = 0,75mm
08 = 0,80mm
others on request

Package Size

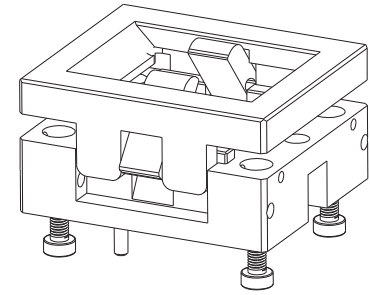
*will be given by the factory after
receipt of the chip datasheet*

Burn-In Sockets BPT Series

BGA PROBE PIN OPEN TOP SOCKET



Open Top Style for Solderless Compression mount
 Accommodates pitch sizes of 0.4/0.5/0.65/0.8/1.0/1.27mm
 Compact size and low Actuation Force
 4-Point pinch design for enhanced electrical contact
 Unique mechanism to eliminate solder ball sticking
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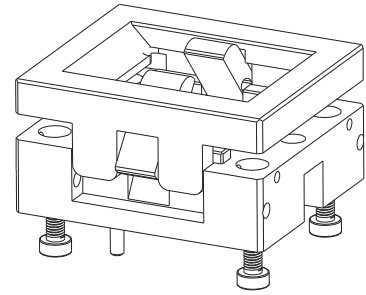
Pitch	No. of Contacts	Package Size(mm)	Part Number
0.4	48	10x12	BPT-048-04-10.0/12
	54	5x5	BPT-054-04-5.0/5
	60	8x10	BPT-060-04-8.0/10
	65	6x8	BPT-065-04-6.0/8
0.5	40	8x9.2	BPT-040-05-8.0/9.2
	48	6x4	BPT-048-05-6.0/4
	56	6x6	BPT-056-05-6.0/6
	64	5x5	BPT-064-05-5.0/5
	105	6x6	BPT-105-05-6.0/6
	141	11.5x13	BPT-141-05-11.5/13
0.65	63	8x10	BPT-063-06-8.0/10
	65	7x11	BPT-065-06-7.0/11
	70	8x8	BPT-070-06-8.0/8
	88	8.1x12	BPT-088-06-8.1/12
0.8	25	5x5	BPT-025-08-5.0/5
	30	5x5	PBT-030-08-5.0/5
	48	9x11	BPT-048-08-9.0/11
	48	9.5x12	BPT-048-08-9.5/12
	54	8x8	BPT-054-08-8.0/8
	56	7x9	BPT-056-08-7.0/9
	56	8x11.6	BPT-056-08-8.0/11.6
	56	8x13	BPT-056-08-8.0/13
	56	8x10	BPT-056-08-8.0/10
	56	8x11.6	BPT-056-08-8.0/11.6
	59	8x11.6	BPT-059-08-8.0/11.6
	60	8x10	BPT-060-08-8.0/10
	60	8x11.6	BPT-060-08-8.0/11.6
	60	11x13	BPT-060-08-11.0/13
	63	7x11	BPT-063-08-7.0/11
	64	7x7	BPT-064-08-7.0/7
64	8x11.6	BPT-064-08-8.0/11.6	
64	8.1x11.1	BPT-064-08-8.1/11.1	

Burn-In Sockets BPT Series

BGA PROBE PIN OPEN TOP SOCKET

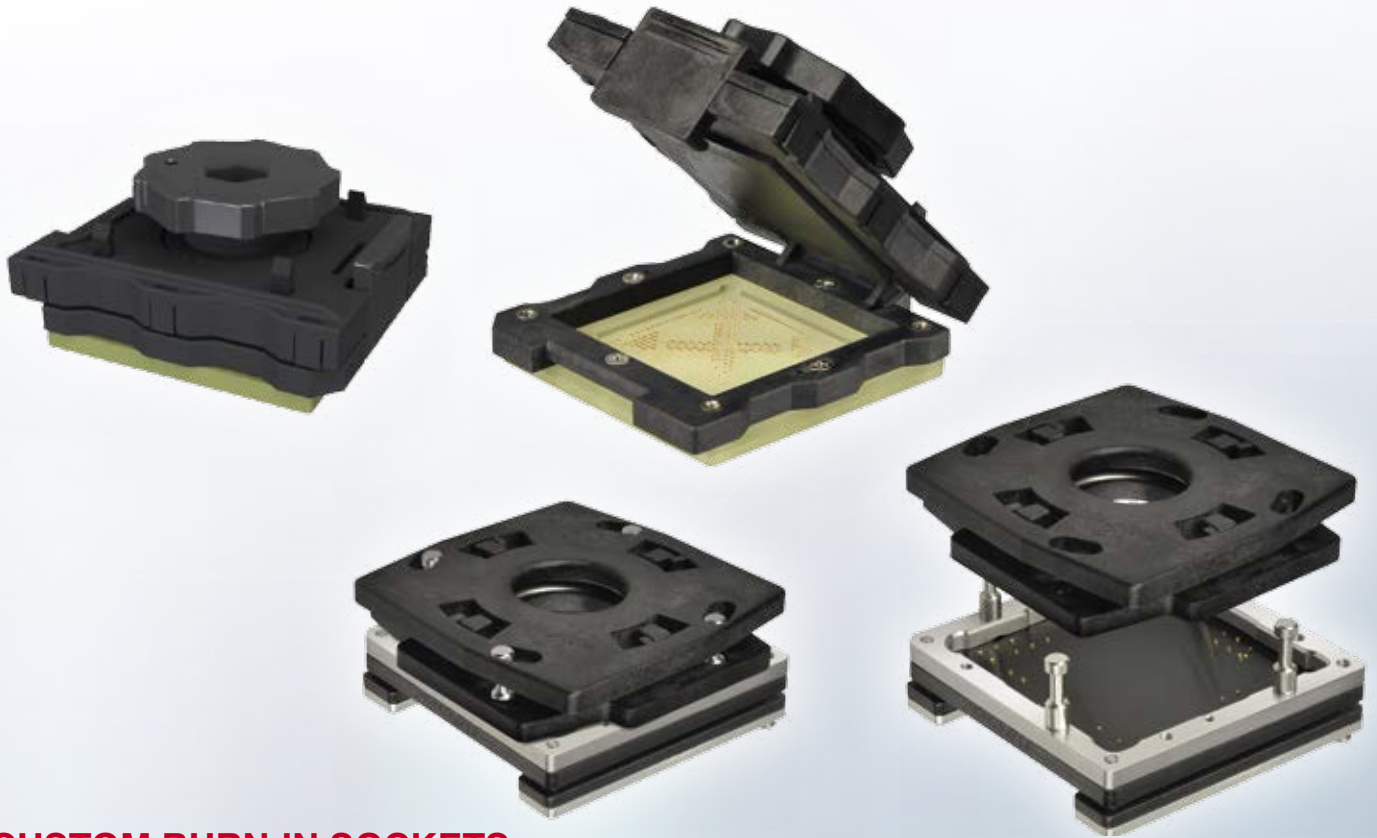


Open Top Style for Solderless Compression mount
 Accommodates pitch sizes of 0.4/0.5/0.65/0.8/1.0/1.27mm
 Compact size and low Actuation Force
 4-Point pinch design for enhanced electrical contact
 Unique mechanism to eliminate solder ball sticking
 Field replaceable package location plate



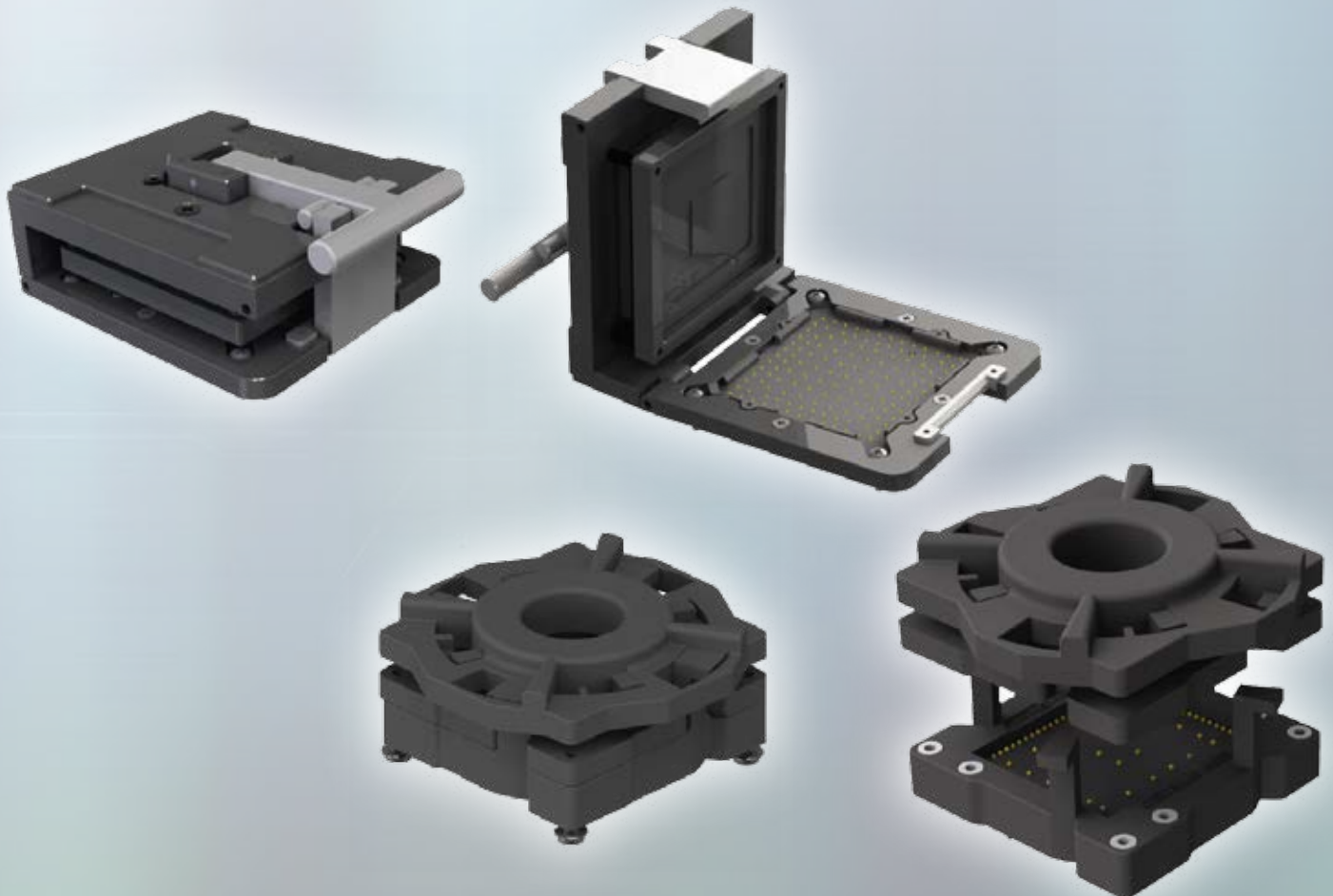
Please note, we will always request the chip data to ensure we offer a compatible socket.

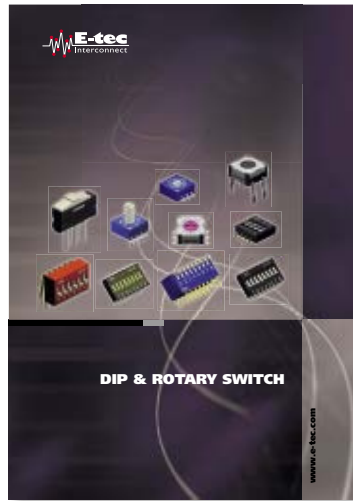
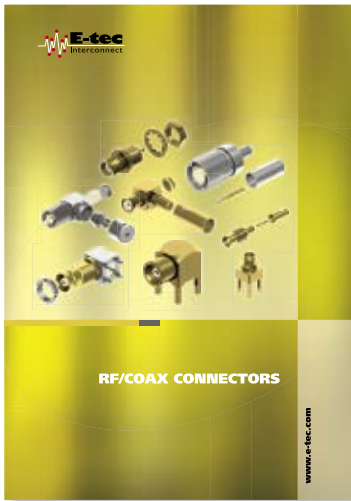
Pitch	No. of Contacts	Package Size(mm)	Part Number
1.0	64	7.95x8.98	BPT-064-10-7.95/8.98
	64	9x9	BPT-064-10-9.0/9
	64	9x11.5	BPT-064-10-9.0/11.5
	64	10.95x11.95	BPT-064-10-10.95/11.95
	66	7.47x11.02	BPT-066-10-7.47/11.02
	72	10x10	BPT-072-10-10.0/10
	80	7x9	BPT-080-10-7.0/9
	80	8x8	BPT-080-10-8.0/8
	80	8x11.6	BPT-080-10-8.0/11.6
	80	8x10	BPT-080-10-8.0/10
	80	9x11.5	BPT-080-10-9.0/11.5
	81	8x8	BPT-081-10-8.0/8
	81	9x9	BPT-081-10-9.0/9
1.27	36	6x6	BPT-036-12-6.0/6
	64	9x9	BPT-064-12-9.0/9
	74	12x12	BPT-074-12-12.0/12
	80	11x11	BPT-080-12-11.0/11
	96	15x15	BPT-096-12-15.0/15
	100	11x11	BPT-100-12-11.0/11



CUSTOM BURN-IN SOCKETS

E-tec Interconnect has over 25 years experience in the design and manufacture of chip test sockets and contactors. This know-how is ideally suited for the fabrication of custom burn-in sockets to satisfy your specific application and we invite you to contact us with your requirements. Your inquiry will receive our prompt review and response.





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